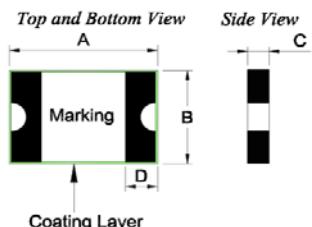


**1、Physical Dimensions(size of 2920)**

Unit:mm

Part Number	A*		B*		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
LSML500/16TC	6.73	8.22	4.80	5.95	0.40	0.70	0.30	T500

\* Dimension is measured after coating


**2、Electrical Characteristics**

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> (Max time to trip)		P <sub>d</sub> typ (W)	R <sub>min</sub> (Ω)	R <sub>1max</sub> (Ω)
	Current(A)	Time(S)							
LSML500/16TC	5.00	10.0	16	50	25.0	7	1.5	0.001	0.012

 I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

 I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

 V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

 I<sub>max</sub>: Maximum fault current device can withstand without damage at rated voltage.

 T<sub>trip</sub>: Maximum time to trip(s) at assigned current.

 P<sub>d</sub> typ: Rated working power.

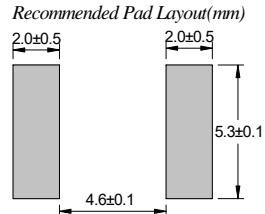
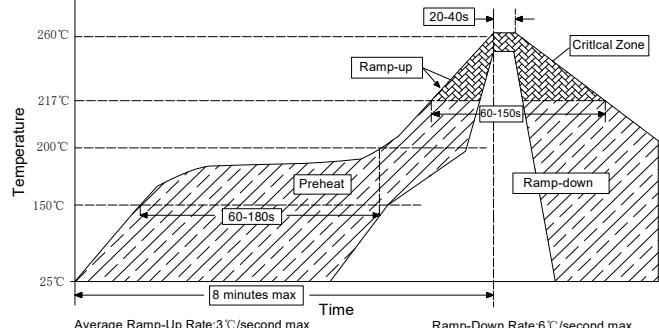
 R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

 R<sub>1max</sub>: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

**3、Thermal Derating**

LSML500/16TC	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	7.60	6.50	5.60	5.00	4.50	3.80	3.20	2.60	2.00
Trip Current(A)	15.2	13.0	11.2	10.0	9.00	7.60	6.40	5.20	4.00

**4、Solder Reflow Recommendations**


Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**5、Package Information**

Packing quantity: 1500 PCS/Reel